

Description

The AP5N10BI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.



 $V_{DS} = 100V I_{D} = 5A$

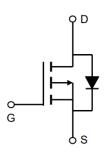
 $R_{DS(ON)} < 125 m\Omega$ @ $V_{GS}=10V$

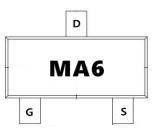
Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP5N10BI	SOT-23	MA6	3000

Absolute Maximum Ratings (T_C=25[°]Cunless otherwise noted)

Symbol	Symbol Parameter		Units
VDS	Drain-Source Voltage	100	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	5	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	3.2	А
Ірм	Pulsed Drain Current ²	16	А
PD@TA=25°C	Total Power Dissipation ³	3.1	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R ₀ JA	Thermal Resistance Junction-ambient(steady state) ¹	100	°C/W
R _θ JA	Thermal Resistance Junction-ambient(t<10s) ¹	40	°C/W





Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100	108		V
D	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =4A		105	125	mΩ
RDS(ON)		V _{GS} =4.5V , I _D =2A		120	145	mΩ
V _{GS} (th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.7	2.5	V
Ipss	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			1	uA
IDSS		V _{DS} =80V , V _{GS} =0V , T _J =85°C			50	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.3	4.6	
Qg	Total Gate Charge (10V)			3.57		
Qgs	Gate-Source Charge	V _{DS} =30V , V _{GS} =10V , I _D =4A		0.76		nC
Qgd	Gate-Drain Charge			0.71		
Td(on)	Turn-On Delay Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3.3		11		
Tr	Rise Time			6		20
Td(off)	Turn-Off Delay Time	I _D =1A		30		ns
T _f	Fall Time			4		
Ciss	Input Capacitance			182		
Coss	Output Capacitance	V _{DS} =50V , V _{GS} =0V , f=1MHz		30		pF
Crss	Reverse Transfer Capacitance]		3.6		
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			2	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	٧

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$ 3.The power dissipation is limited by 150°C junction temperature

^{4.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

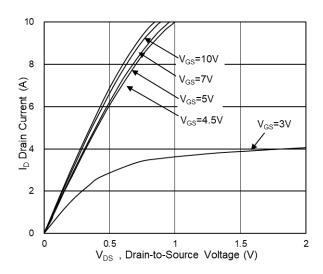


Fig.1 Typical Output Characteristics

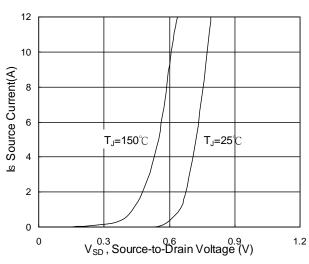


Fig.3 Source Drain Forward Characteristics

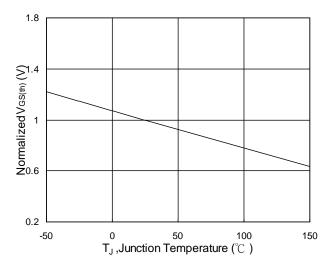


Fig.5 Normalized $V_{GS(th)}$ vs T_J

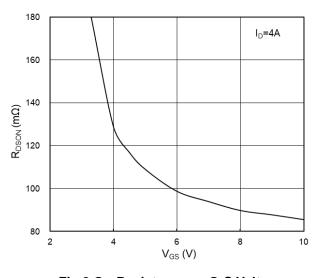


Fig.2 On-Resistance vs G-S Voltage

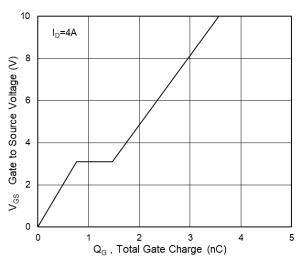


Fig.4 Gate-Charge Characteristics

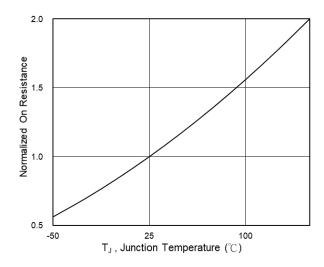
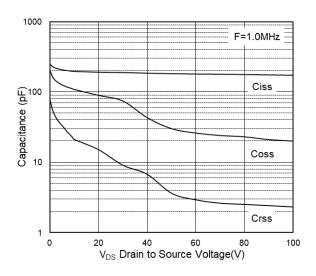


Fig.6 Normalized R_{DSON} vs T_J







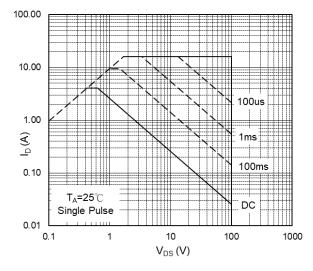


Fig.7 Capacitance

Fig.8 Safe Operating Area

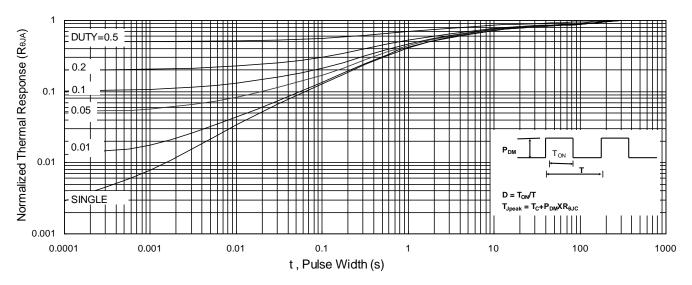


Fig.9 Normalized Maximum Transient Thermal Impedance

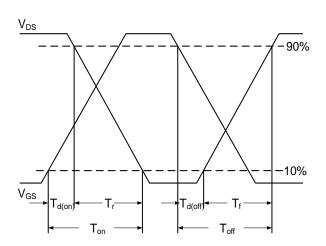


Fig.10 Switching Time Waveform

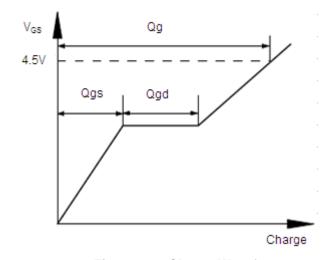
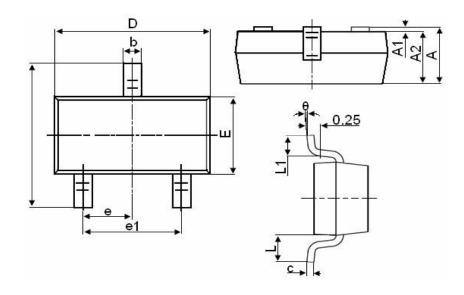


Fig.11 Gate Charge Waveform



Package Mechanical Data-SOT-23



Suma la al	Dimensions in Millimeters	
Symbol	MIN.	MAX.
А	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
С	0.080	0.150
D	2.800	3.000
Е	1.200	1.400
E1	2.250	2.550
е	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°



100V N-Channel Enhancement Mode MOSFET Attention

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Edition	Date	Change
Rve1.0	2020/9/9	Initial release

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